

1200V N-Channel Silicon Carbide Power MOSFET

■ Product Summary

- V_{DS} 1200V
- I_D 57A
- $R_{DS(ON)}$ (at $V_{GS} = 18V$) $< 46m\Omega$ (Typ: $35m\Omega$)
- $R_{DS(ON)}$ (at $V_{GS} = 15V$) $< 52m\Omega$ (Typ: $40m\Omega$)

■ Naming Convention

M	G	X	4	0	N	1	2	0	N
Megain	W: TO-247-3 X: TO-247-4 I: TO-263-7	Rosion Typ. @ $V_{GS}=15V$	N: N P: P	120: 1200V	L: $V_{in}(1\sim 2.5V)$ N: $V_{in}(2\sim 4V)$				

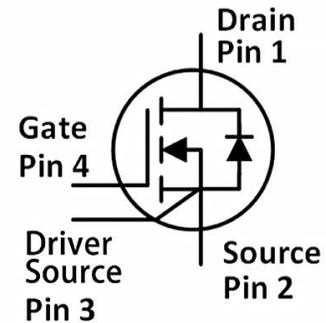
■ Features

- Optimized package with separate driver source pin
- High blocking voltage with low on-resistance
- High-speed switching with low capacitances
- Fast and robust intrinsic body diode
- Easy to parallel

■ Applications

- Switch Mode Power Supplies
- DC/DC converters
- Solar Inverters
- Battery Chargers
- Motor Drives

■ Package & Pin Configuration



■ Ordering Information

Order code	Package	Form	Quantity (PCS)	Marking
MGX40N120N	TO-247-4	Tube	30 / Tube	MGX40N120N

■ Absolute Maximum Ratings

$T_C=25^\circ C$ Unless Otherwise Noted.

Symbol	Parameter	Test Conditions	Value	Units
V_{DS}	Drain-Source Voltage	$V_{GS} = 0V, I_D = 100\mu A$	1200	V
$I_D^{(1)}$	Drain Current – Continuous	$V_{GS} = 18V, T_C = 25^\circ C$	57	A
$I_{DM}^{(2)}$	Drain Current – Pulsed		190	A
$P_D^{(1)}$	Total Power Dissipation	$T_C = 25^\circ C$	255	W
V_{GS}	Recommend Gate Source Voltage		-5/+18	V
	Maximum Gate Source Voltage		-10/+25	V
T_{STG}	Storage Temperature Range		-55 to 175	$^\circ C$
T_J	Operating Junction Temperature Range		-55 to 175	$^\circ C$
T_L	Soldering Temperature		260	$^\circ C$

(1) I_D and P_D are limited by package.

(2) Pulse width is limited by safe operating area.

■ Thermal Characteristics

Symbol	Parameter	Max	Typ	Max	Units
$R_{\theta JC}$	Thermal Resistance Junction to Case	-	0.41	-	$^{\circ}\text{C}/\text{W}$

■ Electrical Characteristics
 $T_J = 25^{\circ}\text{C}$ Unless Otherwise Noted.

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
Static						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 100\mu\text{A}$	1200	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 1200V, V_{GS} = 0V$	-	1	100	μA
I_{GSS}	Gate-Source Leakage Current	$V_{GS} = 18V$	-	1	100	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 10\text{mA}$	1.6	-	3.6	V
$R_{DS(ON)}$	Drain-Source On-state Resistance	$V_{GS} = 18V, I_D = 40\text{A}$	-	35	46	$\text{m}\Omega$
		$V_{GS} = 15V, I_D = 40\text{A}$	-	40	52	$\text{m}\Omega$
Dynamic						
C_{iss}	Input Capacitance	$V_{GS} = 0V, V_{DS} = 800V,$ $f = 1\text{MHz},$ $V_{AC} = 25\text{mV}$	-	1456	-	pF
C_{oss}	Output Capacitance		-	96	-	
C_{riss}	Reverse Transfer Capacitance		-	9	-	
E_{oss}	Coss Stored Energy		-	36	-	μJ
Q_g	Total Gate Charge	$V_{DS} = 800V,$ $V_{GS} = -5/+18V,$ $I_D = 40\text{A}$	-	115	-	nC
Q_{gs}	Gate-Source Charge		-	15	-	
Q_{gd}	Gate-Drain Charge		-	57	-	
$R_{G(int)}$	Internal Gate Resistance	$f = 1\text{MHz}, V_{AC} = 25\text{mV}$	-	1.8	-	Ω
$t_{d(ON)}$	Turn-on Delay Time	$V_{DS} = 800V,$ $V_{GS} = -5/+18V,$ $R_G = 2.5\Omega,$ $I_D = 40\text{A}$	-	13	-	nS
t_r	Turn-on Rise Time		-	19	-	
$t_{d(OFF)}$	Turn-off Delay Time		-	39	-	
t_f	Turn-off Fall Time		-	7	-	
E_{ON}	Turn-on Switching Energy	$V_{DS} = 800V,$ $V_{GS} = -5/+18V,$ $R_G = 2.5\Omega, I_D = 40\text{A}$	-	222	-	μJ
E_{OFF}	Turn-off Switching Energy		-	126	-	μJ
Body Diode Characteristics						
I_S	Continuous Source Current		-	-	57	A
V_{SD}	Diode Forward Voltage	$V_{GS} = 0V, I_S = 20\text{A}$	-	3.8	-	V
t_{rr}	Reverse Recovery Time	$I_S = 20\text{A}, V_{DS} = 800V$ $V_{GS} = -5V$ $di/dt = 2000\text{A}/\mu\text{s}$	-	22	-	nS
Q_{rr}	Reverse Recovery Charge		-	335	-	nC
I_{rrm}	Peak Reverse Recovery Current		-	25	-	A

■ Typical Characteristics

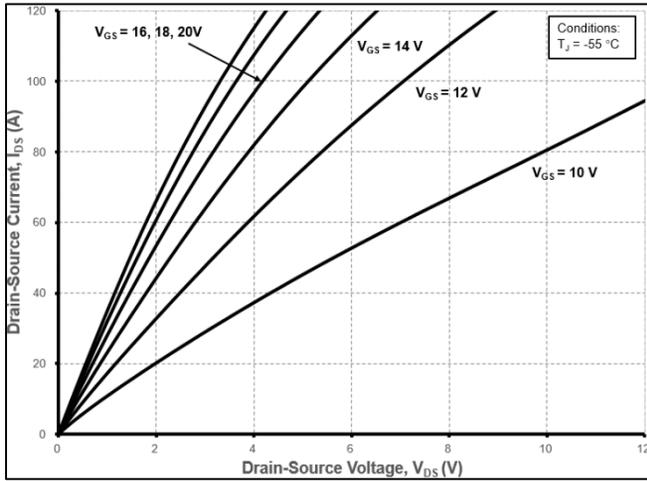


Fig 1. Typical Output Characteristics at $T_J = -55\text{ }^\circ\text{C}$

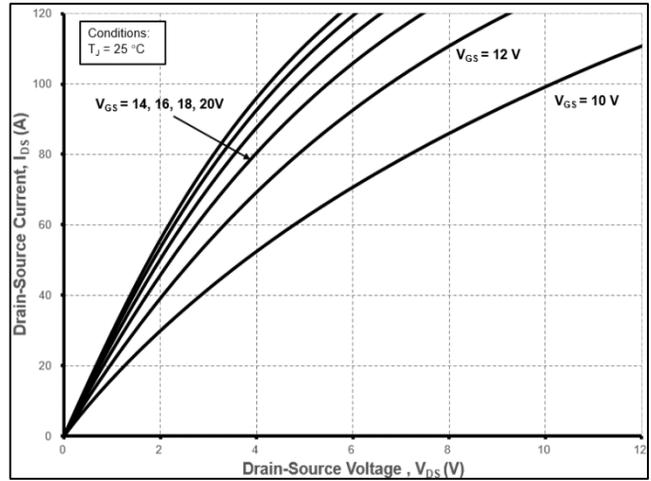


Fig 2. Typical Output Characteristics at $T_J = 25\text{ }^\circ\text{C}$

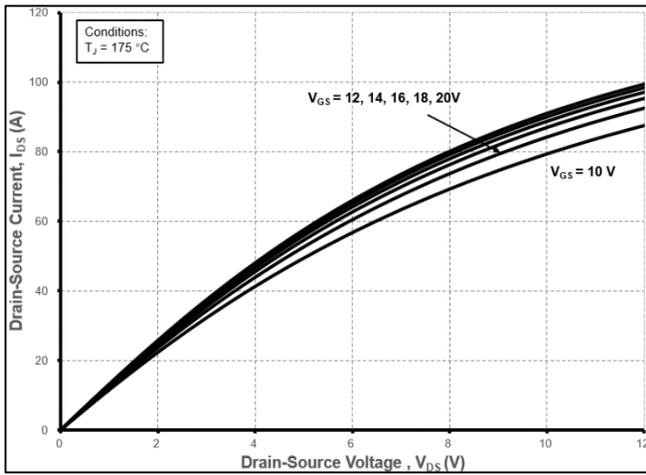


Fig 3. Typical Output Characteristics at $T_J = 175\text{ }^\circ\text{C}$

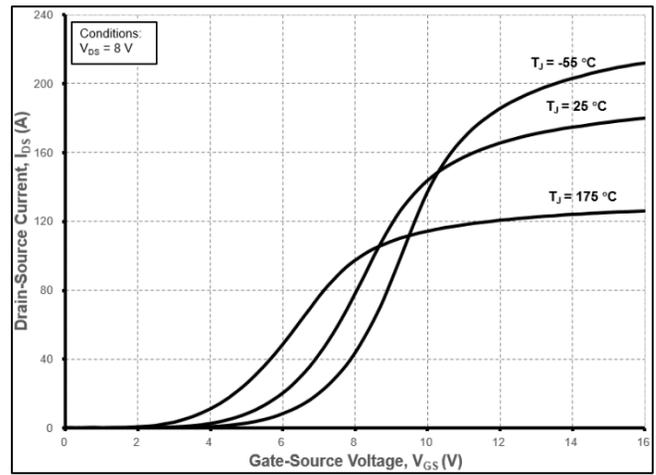


Fig 4. Typical Transfer Characteristics for Various Temperatures

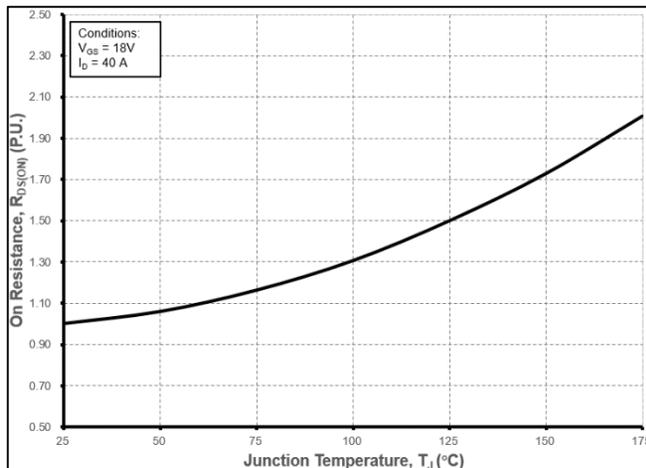


Fig 5. Normalized On-Resistance vs. Temperature

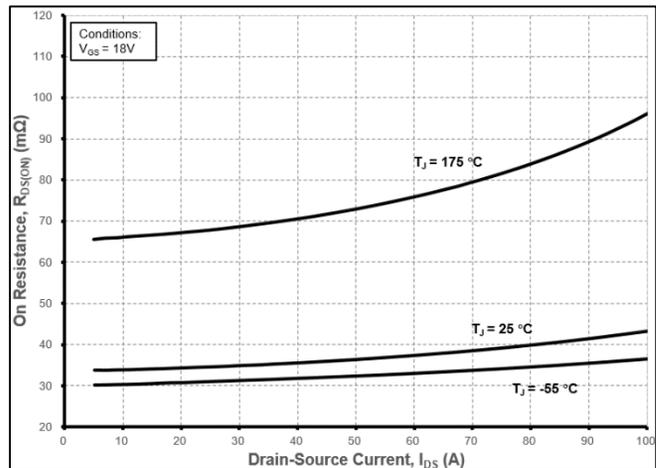


Fig 6. On-Resistance vs. Drain Current for Various Temperatures

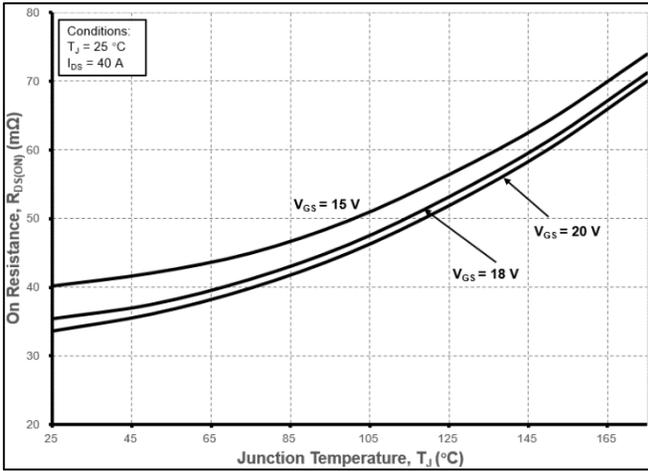


Fig 7. On-Resistance vs. Temperature for Various Gate Voltage

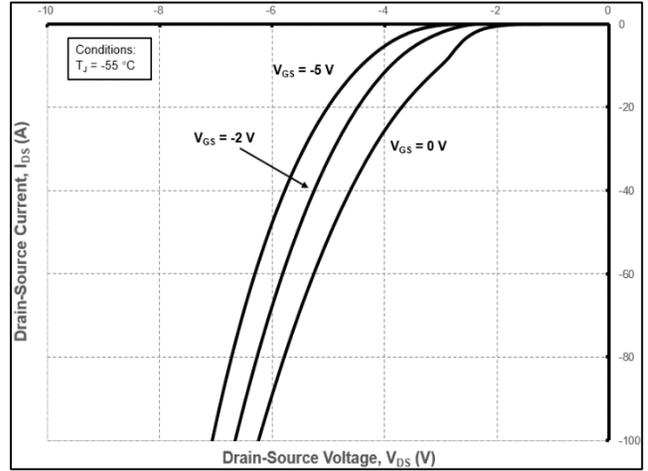


Fig 8. Typical Body Diode Characteristics at $T_J = -55\text{ }^\circ\text{C}$

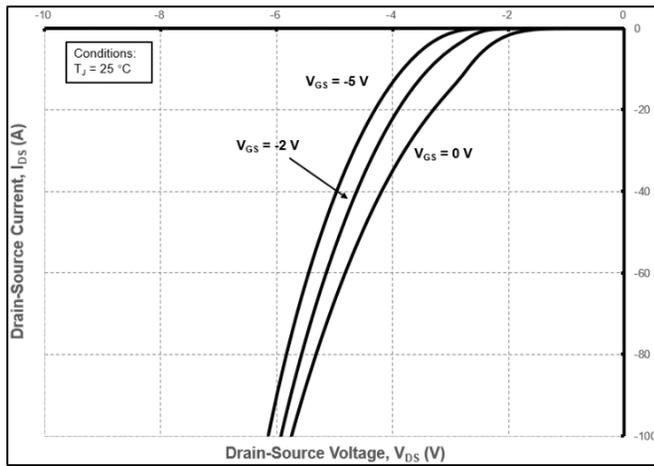


Fig 9. Typical Body Diode Characteristics at $T_J = 25\text{ }^\circ\text{C}$

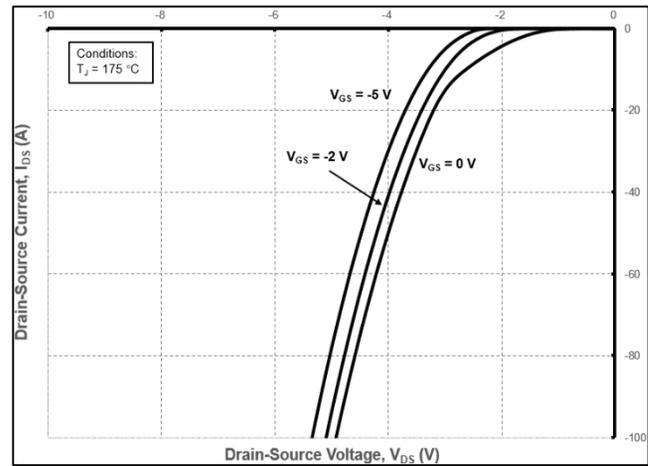


Fig 10. Typical Body Diode Characteristics at $T_J = 175\text{ }^\circ\text{C}$

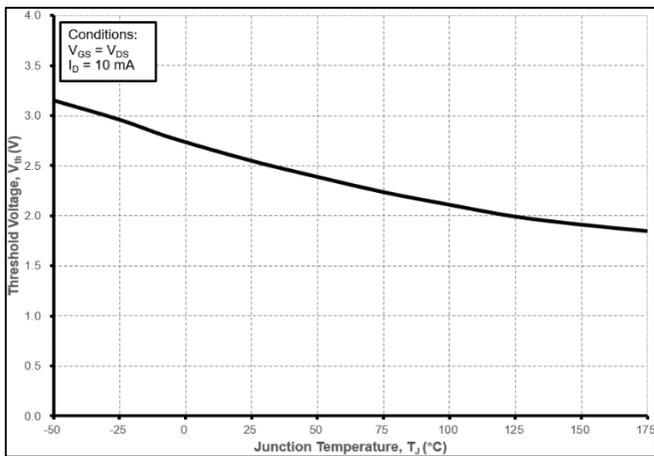


Fig 11. Typical Threshold Voltage vs. Temperature

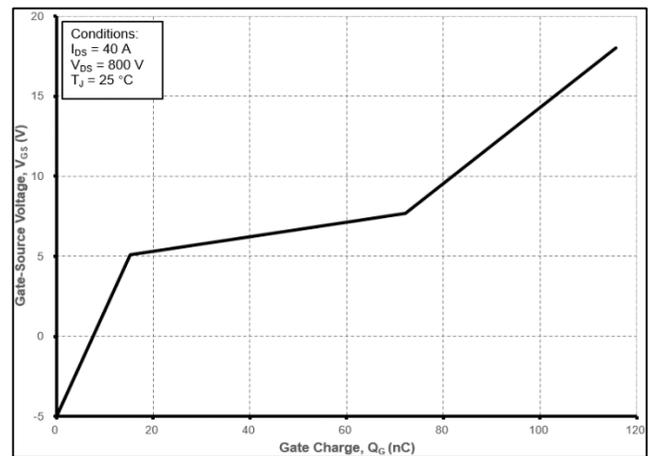


Fig 12. Gate Charge Characteristics

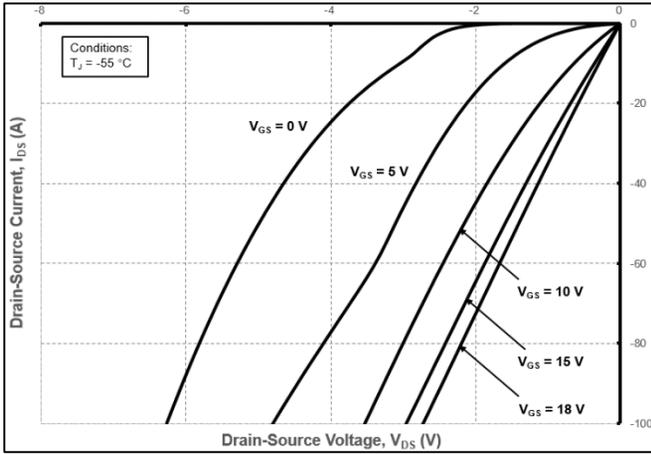


Fig 13. Typical 3rd Quadrant Characteristics at $T_J = -55\text{ }^\circ\text{C}$

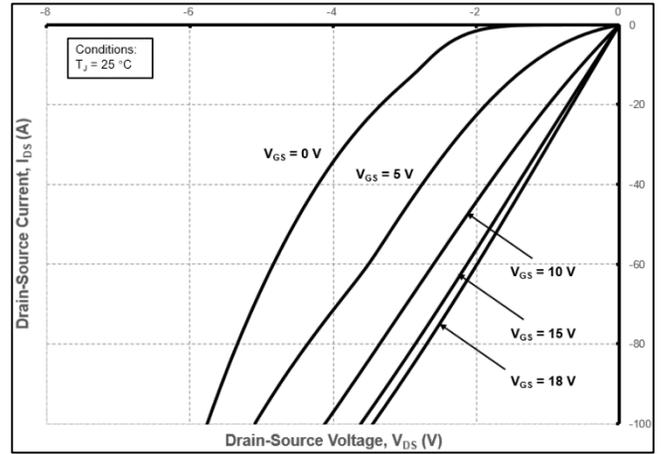


Fig 14. Typical 3rd Quadrant Characteristics at $T_J = 25\text{ }^\circ\text{C}$

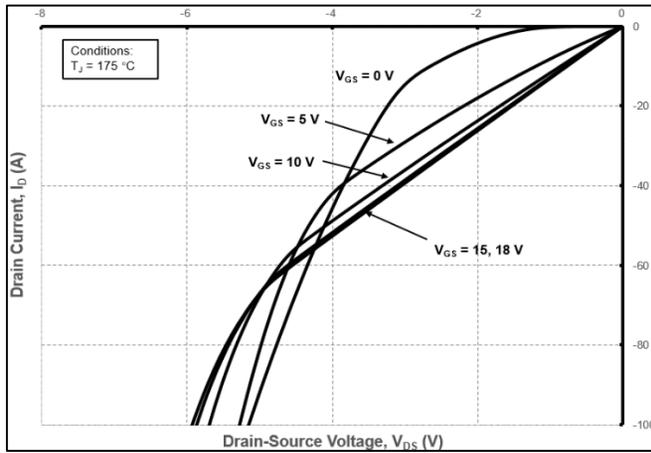


Fig 15. Typical 3rd Quadrant Characteristics at $T_J = 175\text{ }^\circ\text{C}$

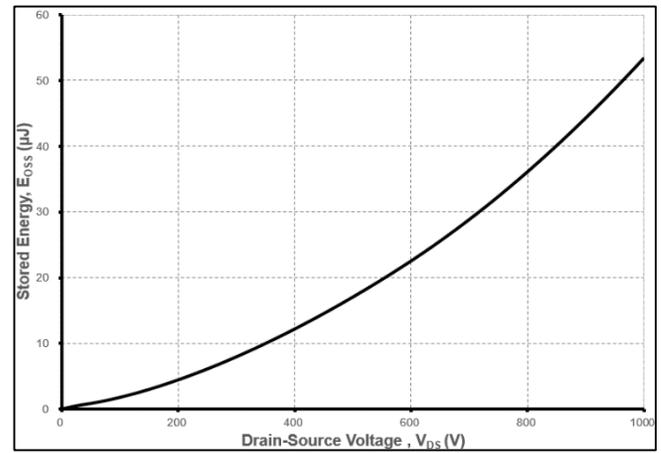


Fig 16. Output Capacitor Stored Energy

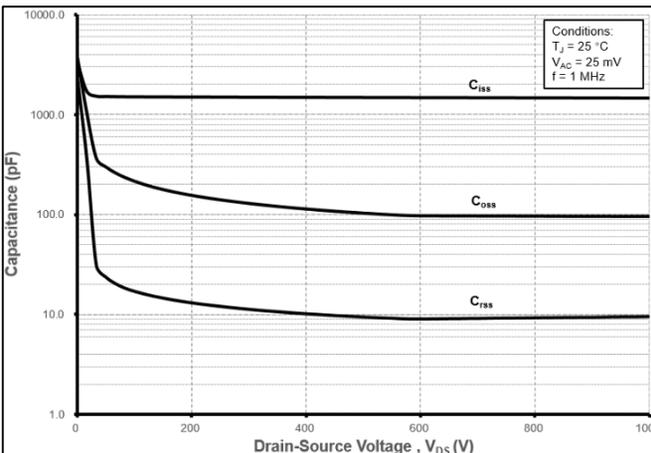


Fig 17. Capacitances vs. Drain-Source Voltage

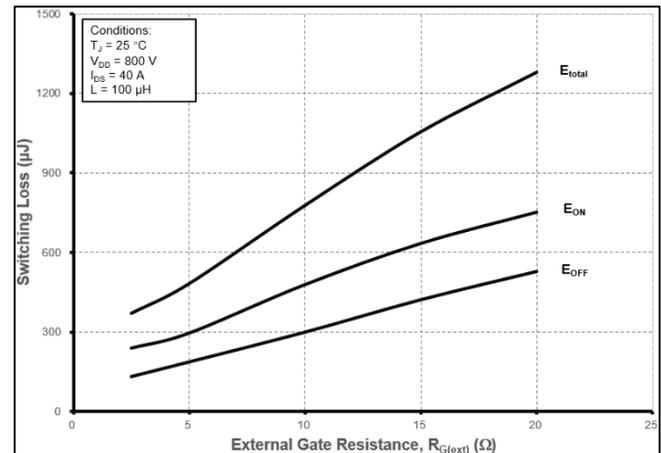


Fig 18. Clamped Inductive Switching Energy vs. $R_{G(ext)}$

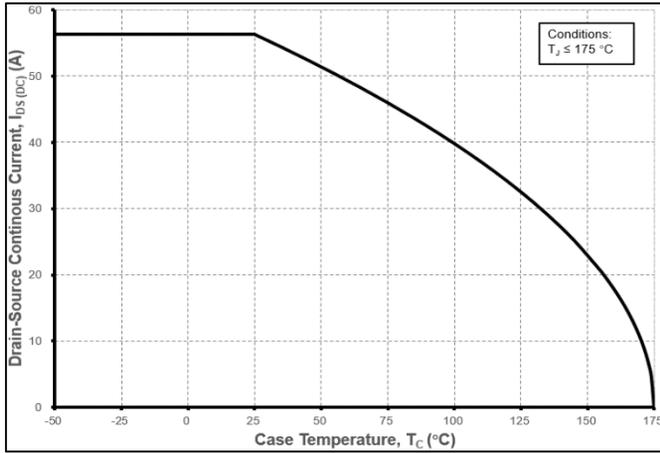


Fig 19. Continuous Drain Current Derating vs. Case Temperature

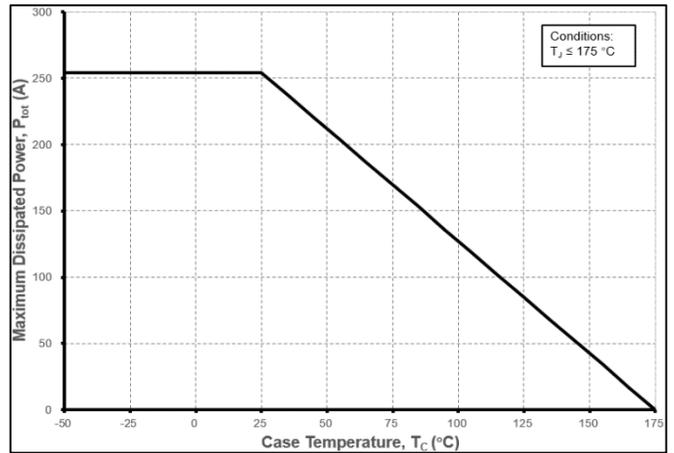


Fig 20. Maximum Power Dissipation Derating vs. Case Temperature

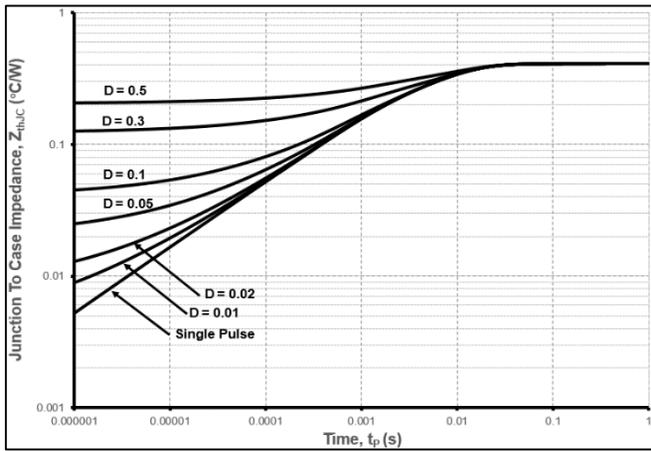


Fig 21. Transient Thermal Impedance (Junction – Case)

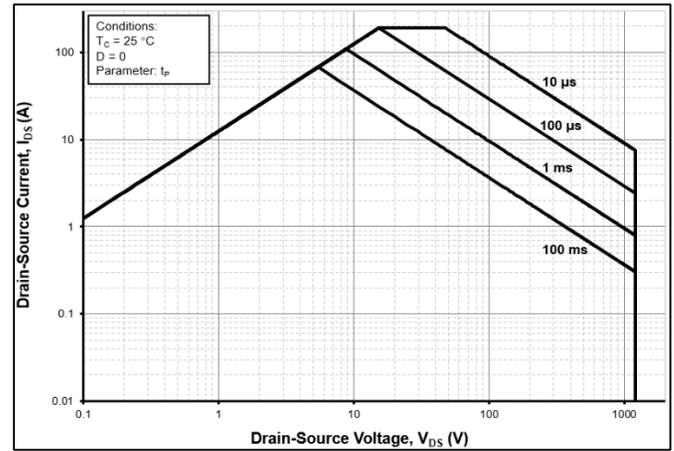
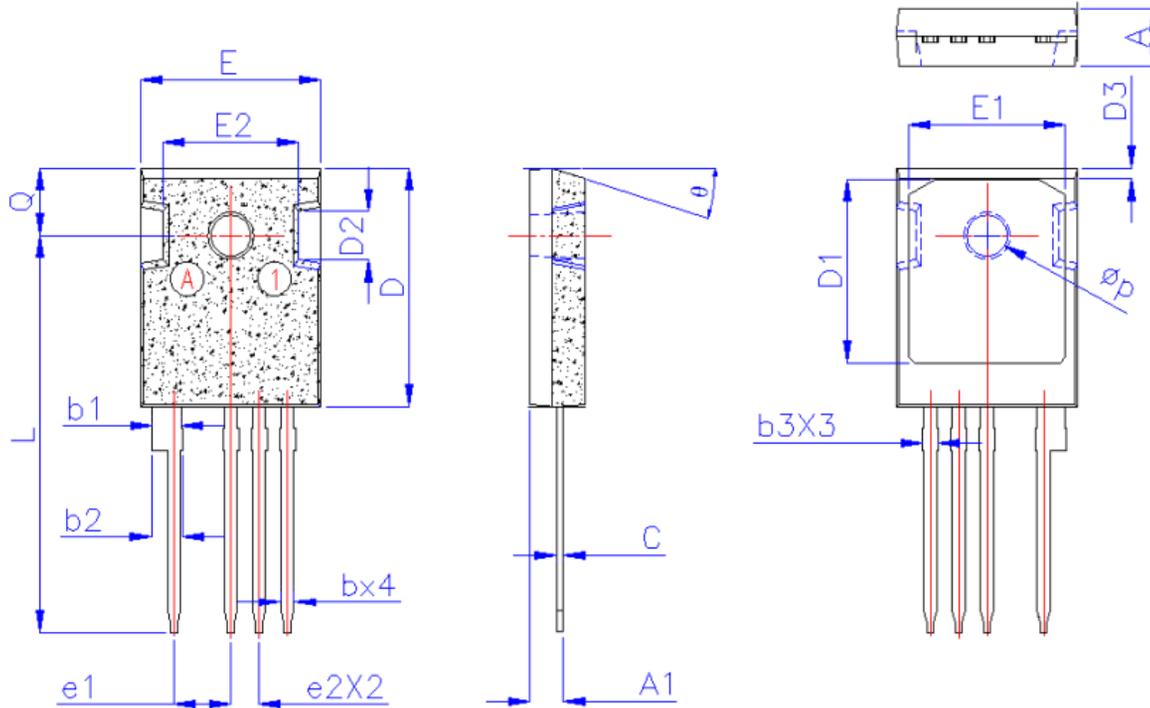


Fig 22. Safe Operating Area

■ Package size

Unit: mm.

TO-247-4:



SYMBDLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
	MIN	TYPE	MAX	MIN	TYPE	MAX
A	4.80	5.00	5.20	0.189	0.197	0.205
A1	2.85	3.00	3.15	0.112	0.118	0.124
b	1.15	1.20	1.25	0.045	0.047	0.049
b1	2.40	2.50	2.60	0.094	0.098	0.102
b2	2.61	2.76	2.91	0.103	0.109	0.115
b3	1.30	1.42	1.57	0.051	0.056	0.062
C	0.55	0.60	0.65	0.022	0.024	0.026
D	20.80	21.00	21.20	0.819	0.827	0.835
D1	15.94	16.24	16.54	0.628	0.639	0.651
D2	4.3 TYPE			0.169 TYPE		
e1	4.93	5.08	5.23	0.194	0.200	0.206
e2	2.39	2.54	2.69	0.094	0.100	0.106
E	15.95	16.15	16.35	0.628	0.636	0.644
E1	13.82	14.02	14.26	0.544	0.552	0.561
E2	12.00	12.20	12.40	0.472	0.480	0.488
L	34.65	35.05	35.45	1.364	1.380	1.396
Q	5.85	5.95	6.05	0.230	0.234	0.238
∅P	3.45	3.60	3.75	0.136	0.142	0.148
θ	17.5°			0.689°		